

PMP8342 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
PCB100	1		Use PMP8342 REVB	Any	Printed Circuit Board	
C1, C2, C3, C4	4	47uF	TPSD476K016R0080	AVX	CAP, TA, 47 μ F, 16 V, +/- 10%, 0.08 ohm, SMD	7343-31
C5, C6, C7, C8, C9, C10, C11, C12	8	470uF	4TPE470MAL	Panasonic	CAP, TA, 470 μ F, 4 V, +/- 20%, 0.01 ohm, SMD	7.3x2.8x4.3mm
C13, C14	2	3300pF	C1005X7R1H332K	TDK	CAP, CERM, 3300 pF, 50 V, +/- 10%, X7R, 0402	0402
C15	1	100pF	GRM1535C1H101JDD5D	MuRata	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
C16, C37	2	0.1uF	C1005X7R1H104K050BB	TDK	CAP, CERM, 0.1 μ F, 50 V, +/- 10%, X7R, 0402	0402
C17, C36	2	1000pF	C1005C0G1E102J	TDK	CAP, CERM, 1000 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
C18, C19, C20, C31, C32, C33	6	100uF	C3225X5R0J107M	TDK	CAP, CERM, 100 μ F, 6.3 V, +/- 20%, X5R, 1210	1210
C21, C22, C23, C24	4	22uF	C3225X5R1C226M	TDK	CAP, CERM, 22 μ F, 16 V, +/- 20%, X5R, 1210	1210
C25	1	2.2uF	GRM188R61C225KAAD	MuRata	CAP, CERM, 2.2 μ F, 16 V, +/- 10%, X5R, 0603	0603
C26, C28, C29	3	1uF	GRM188R61E105KA12D	MuRata	CAP, CERM, 1 μ F, 25 V, +/- 10%, X5R, 0603	0603
C27, C30	2	0.22uF	C1005X7R1C224K050BC	TDK	CAP, CERM, 0.22 μ F, 16 V, +/- 10%, X7R, 0402	0402
C34, C35	2	1uF	C1005X5R1E105K050BC	TDK	CAP, CERM, 1 μ F, 25 V, +/- 10%, X5R, 0402	0402
C100	1	470uF	16SVPE470M	Panasonic	CAP, AL, 470 μ F, 16 V, +/- 20%, 0.01 ohm, SMD	JC0
FID100, FID101, FID102	3		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
J1, J2	2		U.FL-R-SMT-1	Hirose Electric Co. Ltd.	Connector, Ultra-Mini Coaxial, SMD	Ultra small CO-AX SMD
J100, J101, J102	3		1715747	Phoenix Contact	Terminal Block, 5.08mm, 4x1, TH	Terminal Block, 5.08mm, 4x1, TH
J103, J104, J107	3		800-10-002-10-001000	Mill-Max	Header, 100mil, 2x1, TH	Header, 2x1, 100mil, TH
J105	1		N2510-6002-RB	3M	Header (shrouded), 100mil, 5x2, High-Temperature, Gold, TH	5x2 Shrouded header
J106	1		TSW-104-07-G-S	Samtec	Header, 100mil, 4x1, Gold, TH	4x1 Header
R1, R5, R7, R12, R15, R20, R21, R31, R34	9	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
R2	1	10.0k	PCF0402-12-10KBT1	TT Electronics/IRC	RES, 10.0 k, 0.1%, 0.063 W, 0402	0402
R4, R18, R19	3	10.0	CRCW040210R0FKED	Vishay-Dale	RES, 10.0, 1%, 0.063 W, 0402	0402
R6, R17	2	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
R8	1	15.0k	CRCW040215K0FKED	Vishay-Dale	RES, 15.0 k, 1%, 0.063 W, 0402	0402
R10, R22	2	49.9	CRCW040249R9FKED	Vishay-Dale	RES, 49.9, 1%, 0.063 W, 0402	0402
R13	1	49.9k	CRCW040249K9FKED	Vishay-Dale	RES, 49.9 k, 1%, 0.063 W, 0402	0402
R23, R24	2	38.3k	CRCW040238K3FKED	Vishay-Dale	RES, 38.3 k, 1%, 0.063 W, 0402	0402
R100, R101, R102	3	0.001	ERJ-M1WTF1M0U	Panasonic	RES, 0.001, 1%, 1 W, 2512	2512
R103, R104	2	100	CRCW0402100R0FKED	Vishay-Dale	RES, 100, 1%, 0.063 W, 0402	0402
U1	1		TPS40425RHA	Texas Instruments	Dual output, 2-Phase, Stackable PMBUS Synchronous Buck Driverless Controller with AVS Bus, RHA0040B	RHA0040B
U2	1		OKLP-X/45-W12-C	MuRata	45A Power Block Non-Isolated DC/DC Converter, SMD, Body 25.4 x 12.7 mm	Module, 25.4x12.7mm
C38, C39	0	3300pF	C1005X7R1H332K	TDK	CAP, CERM, 3300 pF, 50 V, +/- 10%, X7R, 0402	0402

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C40	0	100pF	GRM1535C1H101JDD5D	MuRata	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
R3, R9, R27, R33	0	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100 k, 1%, 0.063 W, 0402	0402
R11, R14, R16, R25, R29	0	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
R26	0	10.0k	PCF0402-12-10KBT1	TT Electronics/IRC	RES, 10.0 k, 0.1%, 0.063 W, 0402	0402
R28	0	10.0	CRCW040210R0FKED	Vishay-Dale	RES, 10.0, 1%, 0.063 W, 0402	0402
R30	0	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
R32	0	15.0k	CRCW040215K0FKED	Vishay-Dale	RES, 15.0 k, 1%, 0.063 W, 0402	0402

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